

Abstract of the Disclosure:

Interface parameters for a plurality of semiconductor devices, particularly parameters for output drivers (i.e. on chip driver) and terminations (i.e. on die termination) for double
5 data rate dynamic random access memories, are aligned using a calibration reference which is common to the semiconductor devices and is connected to calibration connections on the semiconductor devices. The semiconductor devices are calibrated in succession, in each case individually, and the
10 calibration connection on the respective semiconductor device which is currently performing calibration is connected to an internal calibration unit by an internal switching unit in the process, and the calibration connections on all other semiconductor devices are terminated to a high impedance
15 internally.

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